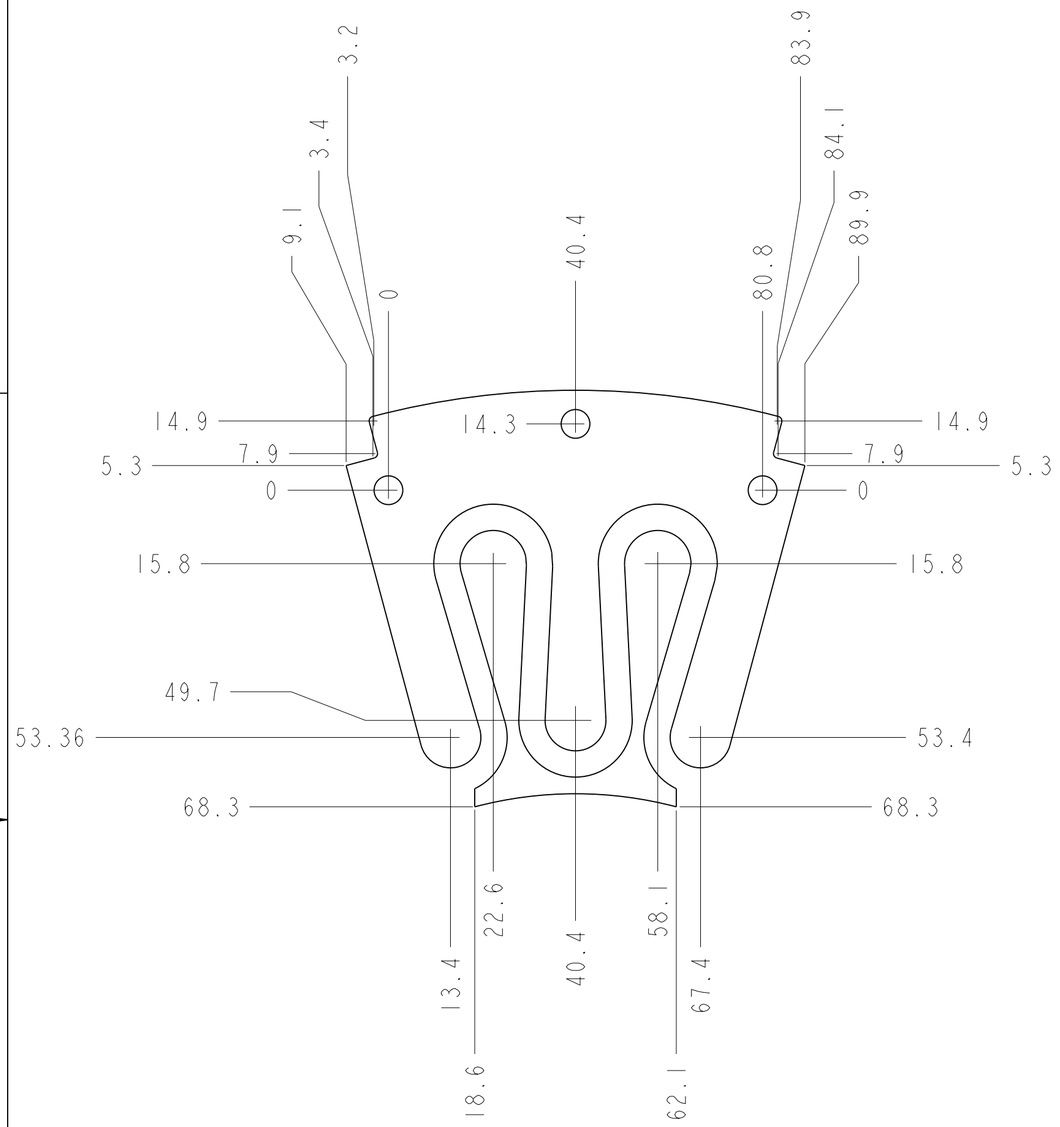
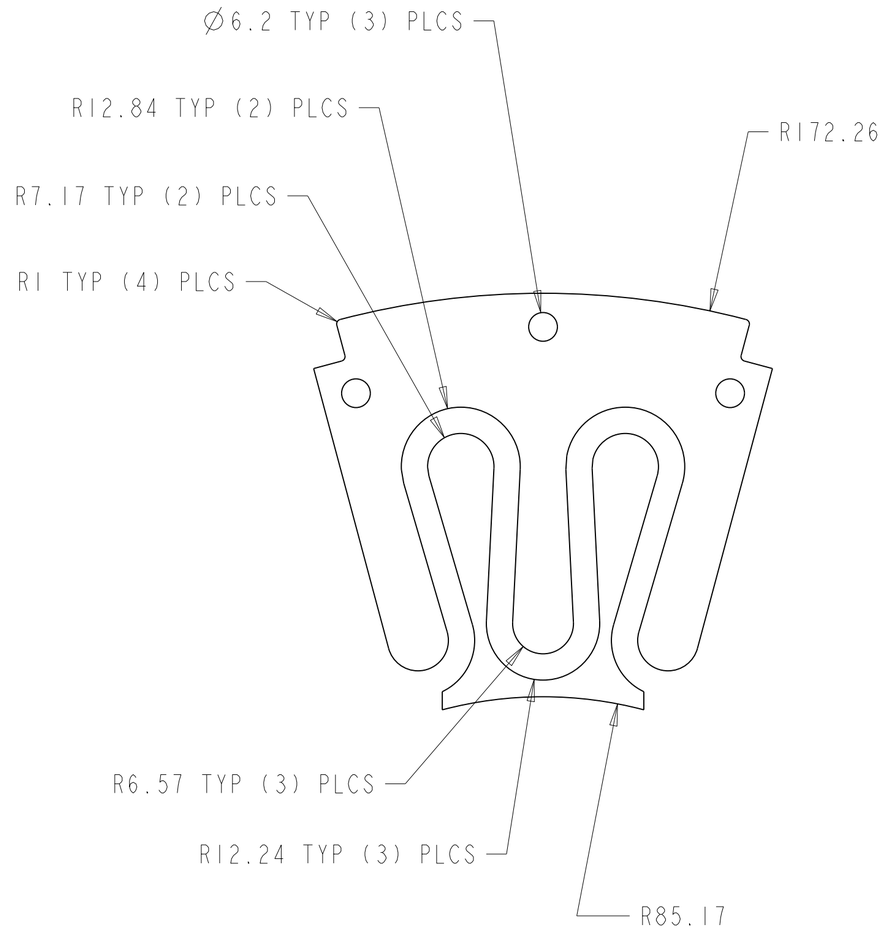
DESCRIPTION	MATERIAL	MAT. LOCATION
	BRYTE E01189-2M	-



0.1



DWG. NO. 21f4253 | SIZE 1 | REV. 1 | SH. 1

REV	DWG	CHK	ZONE	DATE	CHANGES

UNLESS OTHERWISE SPECIFIED

TOLERANCES		
	X.X ± 0.1	FRAC. ± 1/64
	X.XX ± 0.01	Angles ± 0.50°
	X.XXX ± 0.001	FINISH 125 (µin)

DO NOT SCALE PRINT

THREADS ARE CLASS 2

CHAMFER ENDS OF ALL SCREW TREADS 30°

CUT ROUND, 1.5 THREAD RELIEF ON MACHINED THREADS

BREAK EDGES .016 MAX. ON MACHINED WORK

REMOVE BURRS, WELD SPLATTER & LOOSE SCALE

IN ACCORDANCE WITH ASME Y14.5M & B46.1

SHOP ORDERS

ACCT NO.	NO. REQD	
DEL TO		
SURFACE TREATMT		
IDENT METHOD	TAG	
PROJECT NUMBER	ATL-IP-ED-0032	
PROJECT NAME	US ATLAS SILICON SUBSYSTEM	
DWG BY	D UKEN	DATE 19-Jun-01
CHK BY	J WIRTH	DATE
APR BY	E ANDERSSEN	DATE

SER NO. -

DATE ISSD -

DATE REQD -

US ATLAS SILICON SUBSYSTEM (logo)

ERNEST ORLANDO LAWRENCE
BERKELEY NATIONAL LABORATORY
UNIVERSITY OF CALIFORNIA - BERKELEY

ATLAS PIXEL DETECTOR
DISK SECTOR, MODULE LOCAL SUPPORT
CYANATE ESTER FOR FOAM

MICROFILMED:	DWG. TYPE	SHOWN ON	SCALE: 1.000 DO NOT SCALE PRINTS
	PART	21F350	SHEET 1 OF 1
PATENT CLEAR:	DESIGN ACCT. NO.	CATEGORY CODE	DWG. NO. 21f4253 SIZE REV. 1
	SEE J.O.	AP6110	

Dwg. File: 21F425 Model File: 21F425

Rev. 1/8/2001 ATLAS